

LINQBOND DA-8030

Conductive Die Attach



- Good thermal and electrical conductivity
- Excellent adhesion
- Low temperature cure

LINQBOND DA-8030 is a single-component, silver-filled, electrically conductive die attach adhesive. It is engineered to provide exceptional thermal and electrical conductivity, ensuring efficient heat dissipation and reliable electrical connections. Its excellent adhesion properties allow for secure bonding to various substrates, such as metal and ceramic. Additionally, the modified epoxy's low-temperature curing capability minimizes thermal stress on components.

LINQBOND DA-8030 is designed as a die attach for thin packages such as memory cards, CCD and CMOS assemblies. It can also be used for other applications such as consumer electronics, automotive sensors, and diodes.

Cure Schedule

- 60 minutes at 120°C

Uncured properties

Property	Value	Unit
Chemistry	Epoxy	–
Filler	Silver	-
Viscosity at 25 °C (5rpm)	20700	cps
Thixotropic index (0.5/5rpm)	3.5	-
Work life @25°C	24	hours

Cured properties

Property	Value	Unit
Volume Resistivity	13	mΩ.cm
Thermal Conductivity	4.5	W/m.K
Glass Transition Temperature (Tg)	92	°C
Coefficient of Thermal Expansion (CTE) 1	57	ppm
Coefficient of Thermal Expansion (CTE) 2	147	ppm
Die Shear Strength* @ 25°C	16	kg-f
@ 260°C	1.5	

* Based on 2mm x 2mm bare Si die on a Ag plated substrate using recommended cure condition.

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Curing Conditions:

- Ramp to 120°C and hold for 60 minutes
- Ramp rate 5°C/min

These conditions serve as a reference only. Please establish the curing conditions based on the product's specific requirements.

Precautions:

1. When the material is taken out of refrigeration, thaw it first prior to use. Syringe should be placed vertically while thawing. Thaw 10cc syringe for 1 hour and 100cc package for >4 hours. Medium syringes should be thawed accordingly. Keep in an airtight container at room temperature.
2. The adhesive cannot be refrozen once exposed to room temperature.
3. Wear appropriate protective equipment and minimize direct contact with the human body. Refer to the Material Safety Data Sheet (SDS) before use.

Please note that the provided information is based on available data and typical conditions. For specific applications and detailed test results, refer to the actual test data and conduct appropriate certifications.

Storage and Handling

Store and transport in a -15°C temperature. Keep away from fire and heat sources. It is strictly forbidden to store in outdoor environments.

- Shelf life at below -15 °C is 365 days.

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